



**INTRODUCES**

**MICRO ELECTRONICS  
PROTO & PRODUCTION**



- SUB 2-MIL LINES • .25 MM PITCH
- STACKED BLIND & BURIED VIAS
- ULTRA THIN MULTI LAYER BOARDS  
(12 LAYERS, 28-MIL THICKNESS)

**Complete Design Assistance**

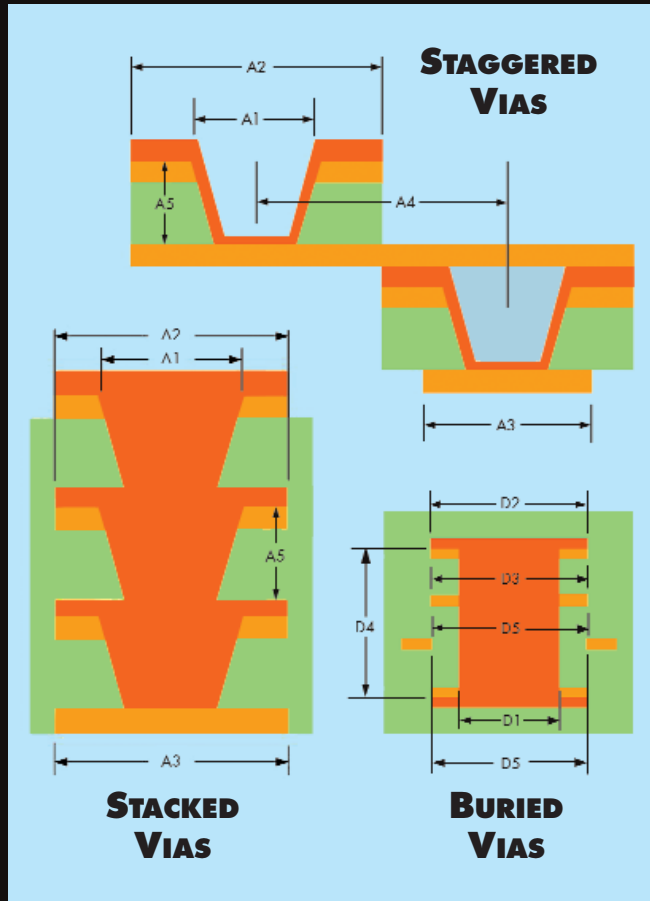
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# MICRO ELECTRONICS

## MICRO ELECTRONICS VIA STRUCTURES



For Complete Design Guideline Details, Visit:  
[www.micropcb.com](http://www.micropcb.com)

## MICRO ELECTRONICS CAPABILITIES

### Microvia from Outer Layer to 1st Inner Layer

A1 Blind/Buried via laser drill diameter	.002"
A2 Laser drill capture pad diameter	A1 + .004"
A3 Laser drill target pad diameter	A1 + .004"
A4 Distance center to center staggered vias	.005"
A5:A1 Laser via plating aspect ratio	>1:1

### Filled (Copper) Mechanical Drill Buried Via

D1 Buried via mechanical drill diameter	.004"
D2 Mechanical drill capture pad diameter	D1 + .008"
D3 Mechanical drill target pad diameter	D1 + .008"
D4 Dielectric thickness	.005"
D5 Innerlayer antipad clearance diameter	D1 + .012"
D4:D1 Mechanical via plating aspect ratio	>16:1

### LPI Soldermask

Minimum thickness	.0005"
Registration tolerance	+/- .001"
Minimum SMD pad spacing for mask between pads	.005"
Minimum web width	.002"

### Legend Specifications

Minimum text line width	.0025"
Registration tolerance	+/- .003"
Minimum character height	.015"

## COMPLETE DESIGN ASSISTANCE

- Design Assistance to Optimize Costs
- Impedance Stack-up Assistance
- Design for Manufacturability (DFM) Assistance

**MILITARY • MEDICAL • AUTOMOTIVE**

Please call us at:  
**1.800.763.7503**  
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